# MA2Z7200G

### Silicon epitaxial planar type

For high frequency rectification

#### Features

- Forward current (Average)  $I_{F(AV)} = 500$  mA rectification is possible
- High-density mounting is possible

 Package
Code SMini2-F3
Pin Name 1: Anode

#### 2: Cathode

#### Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit
Reverse voltage	V <sub>R</sub>	40	V
Maximum peak reverse voltage	V <sub>RM</sub>	40	V
Forward current (Average)	I <sub>F(AV)</sub>	500	mA
Non-repetitive peak forward surge current *	I <sub>FSM</sub>	2	А
Junction temperature	Tj	125	°C
Storage temperature	T <sub>stg</sub>	-55 to +125	°C

Marking Symbol: 2L

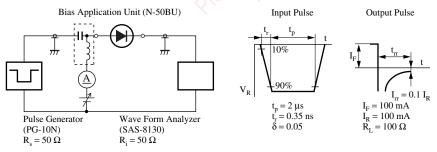
Note) \*: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

#### Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

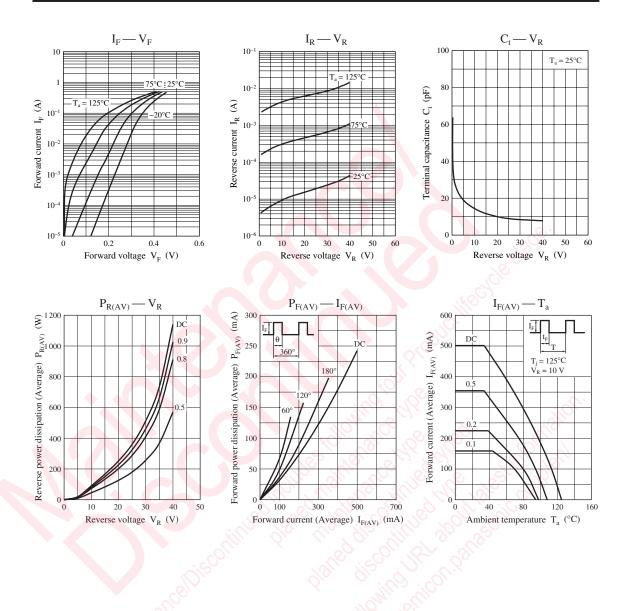
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	VF	I <sub>F</sub> = 500 mA	20	SOL	0.55	V
Reverse current	IR	V <sub>R</sub> = 35 V	Jan J	0	100	μΑ
Terminal capacitance	C <sub>t</sub>	$V_R = 0 V, f = 1 MHz$	2.2	60		pF
Reverse recovery time *	t <sub>rr</sub>	$I_F = I_R = 100 \text{ mA}$		5		ns
		$I_{rr} = 0.1 I_R, R_L = 100 \Omega$				

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

- 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
- 3. Absolute frequency of input and output is 400 MHz.
- 4.\*: t<sub>rr</sub> measurement circuit

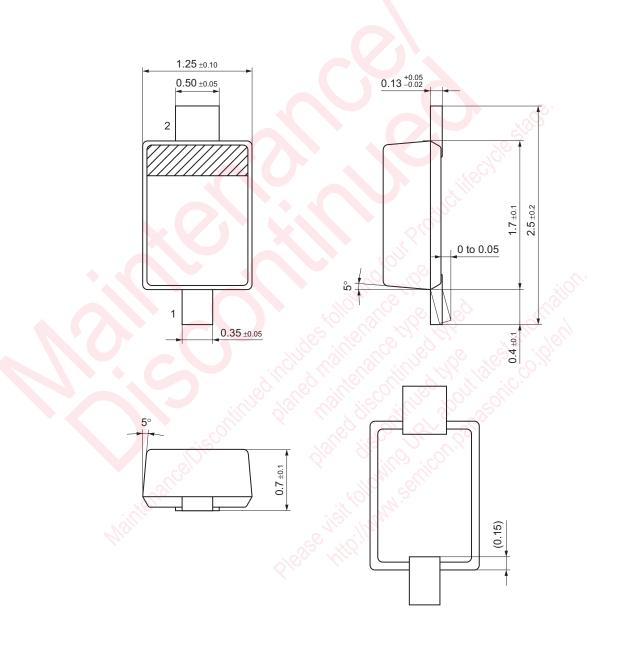


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SMini2-F3

Unit: mm



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